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Daetec Products

Snap-cure, 100% solids, i-line (365nm) curing

UV Cure	Application	Form	Therm Resist (C)	Cleans
DaeCoat 555	Adhesion, bonding	low viscosity, <10cps	>200	DIW
DaeCoat 575R1	Adhesion, bonding, dam, syringe application	Gel form, semi-solid	>200	DIW
GuardCoat L252	Hard Coat for dicing & drilling, thick, water resistant	high viscosity, very hard when cured	<125	IPA
GuardCoat L652			<100	DaeClean 160, 10% in DIW
GuardCoat R11B	Hard Coat, thin, water resistant	low viscosity, med hard when cured	<150	DaeClean 160, 10% in DIW

Evaporative-cure, aqueous-based chemistries

Evaporative Cure	Application	Form	Therm Resist (C)	Cleans
DaeCoat 528G3	Temporary protective coating for laser & mechanical handling	med viscosity, spin ~10um, spray w/IPA	>200	DIW
DaeCoat 537	Temporary protection, thick coatings, high modulus, hard	high viscosity for thick films, spray 1:1 DIW:IPA	>250	DIW

Film Coatings	Application	Form	Therm Resist (C)	Cleans
GuardCoat F252	UV cure film versions of L252 & L652, respectively, thick hard coat for dicing/drilling	100um coating on PET plastic	<125C, resists water	IPA
GuardCoat F652			<100C, resists water	DaeClean 160, 10% in DIW
DaeCoat F525	UV cure film version of 528G3, laser & mechanical protection	<10um coating on PET plastic	>200C	DIW
DaeBond F357	UV cure temporary bonding carrier, laminate of silicone & PI	Thck coating on PI	>250C, resists water and chemicals	DaeClean 330

Cleaners	Application	Form	Processing	Rinsing
DaeClean 160	Cleaning/dissolving of water-resistant DaeCoat products	Concentrated liquid, dilute 10% in DIW	Spray, immersion, agitation or heating	DIW
DaeClean 330	Cleans/dissolve of DaeBond F357	Liquid, ready to use		IPA

Products in red: under development

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